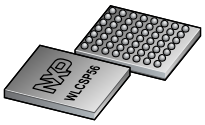

SOT1914-2

WLCSP56, wafer level chip-scale package; 56 bumps, 0.4 mm pitch, 3.455 mm x 3.06 mm x 0.495 mm body (backside coating included)

6 May 2020 **Package information**

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP56
Package style descriptive code	WLCSP (wafer level chip-size package)
Mounting method type	S (surface mount)
Issue date	06-04-2020
Manufacturer package code	98ASA01508D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	3.425	3.455	3.485	mm
package width	3.03	3.06	3.09	mm
seated height	-	0.495	0.53	mm
nominal pitch	-	0.4	-	mm
actual quantity of termination	-	56	-	

WLCSP56, wafer level chip-scale package; 56 bumps, 0.4 mm pitch, 3.455 mm x 3.06 mm x 0.495 mm body (backside coating included)

2 Package outline

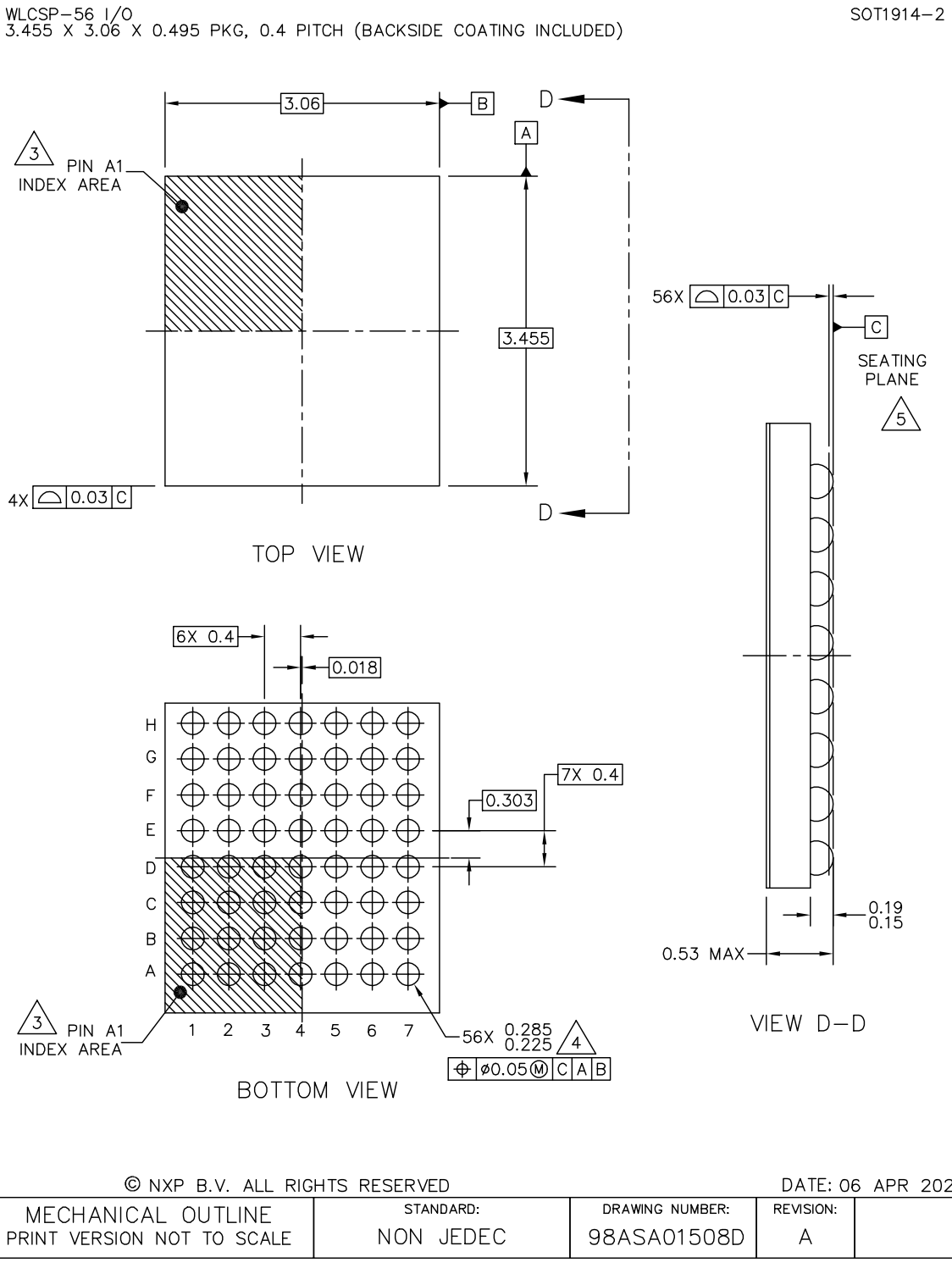

Figure 1. Package outline WLCSP56 (SOT1914-2)

3 Soldering

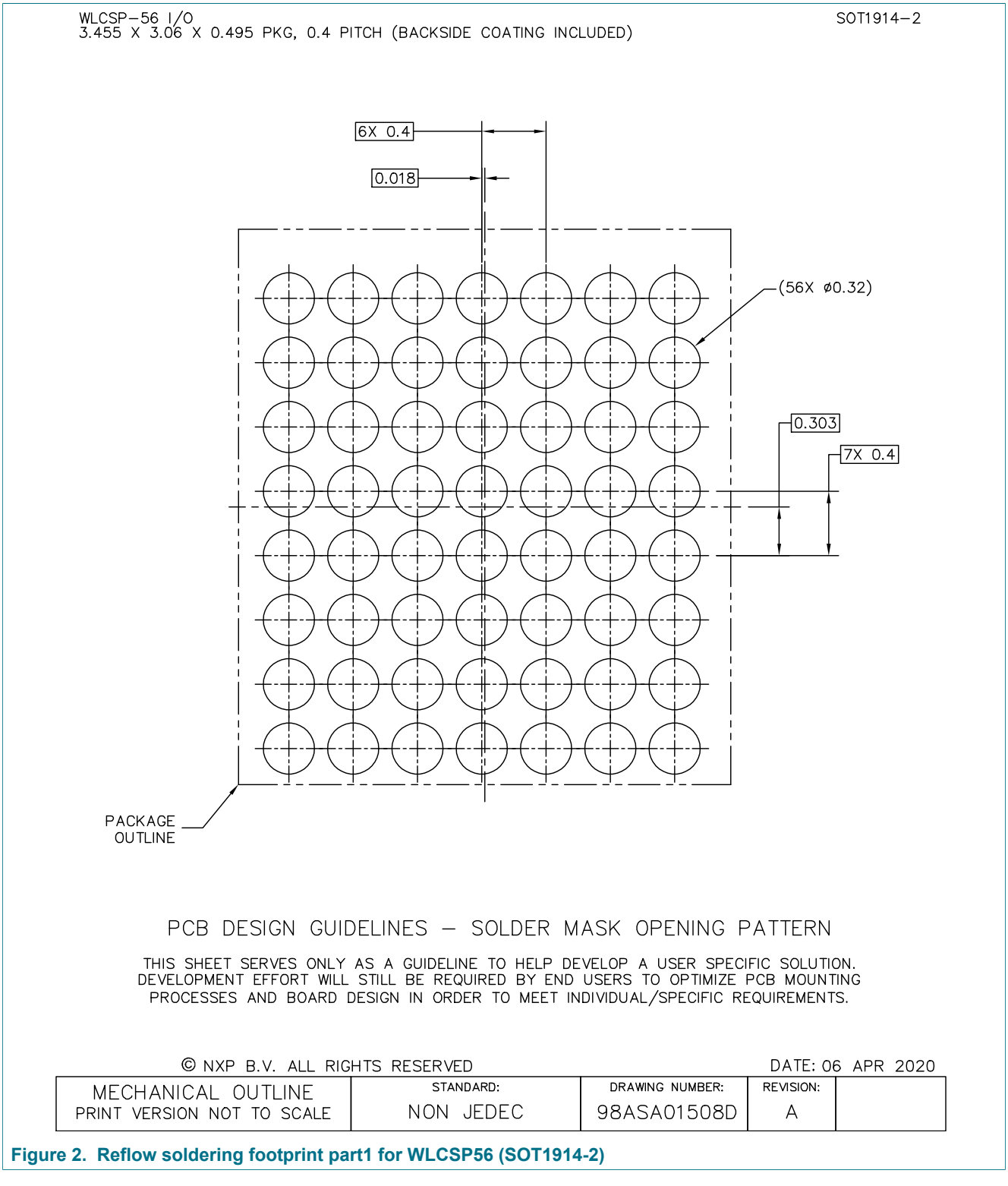

Figure 2. Reflow soldering footprint part1 for WLCSP56 (SOT1914-2)

WLCSP56, wafer level chip-scale package; 56 bumps, 0.4 mm pitch, 3.455 mm x 3.06 mm x 0.495 mm body (backside coating included)

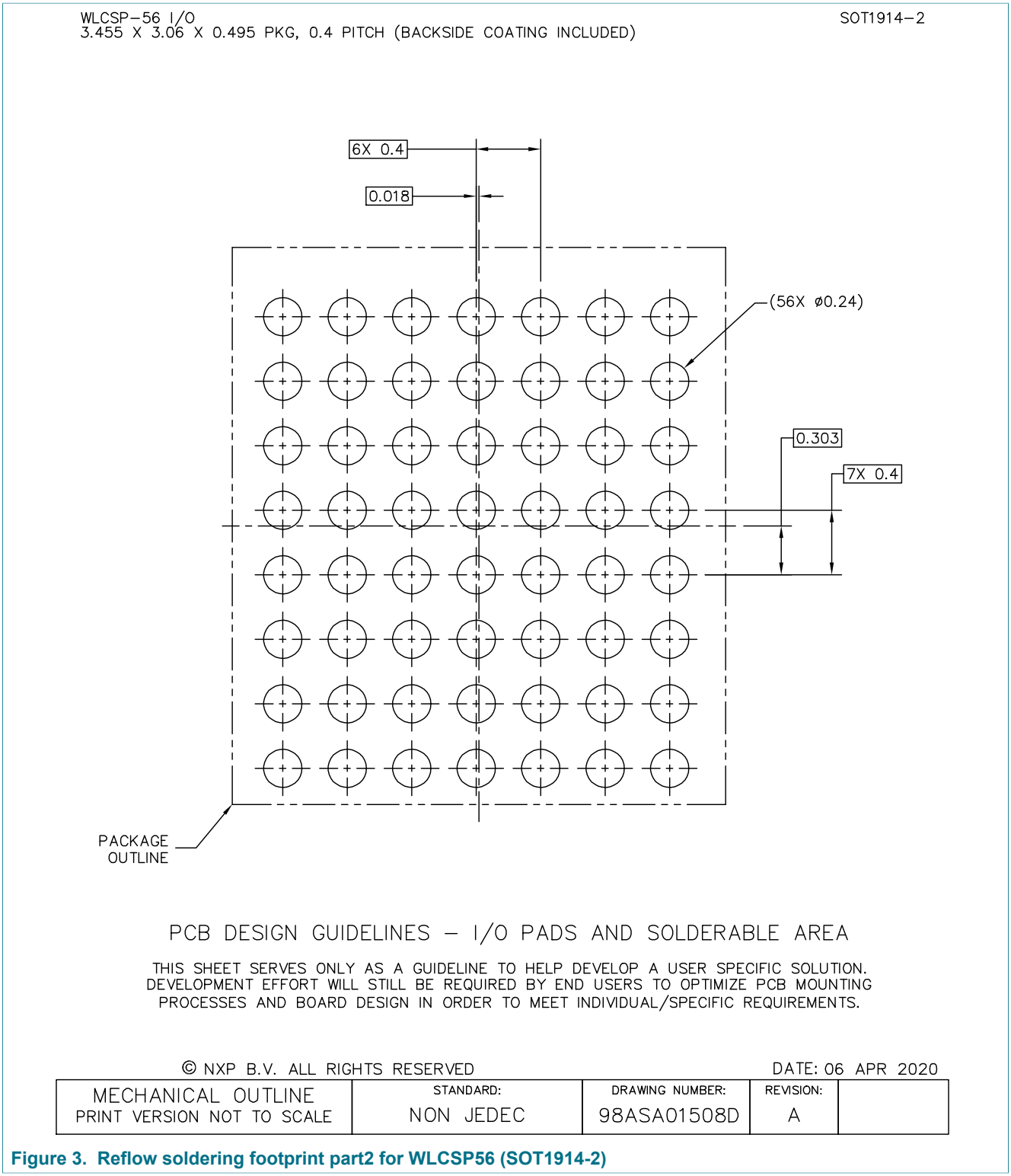

Figure 3. Reflow soldering footprint part2 for WLCSP56 (SOT1914-2)

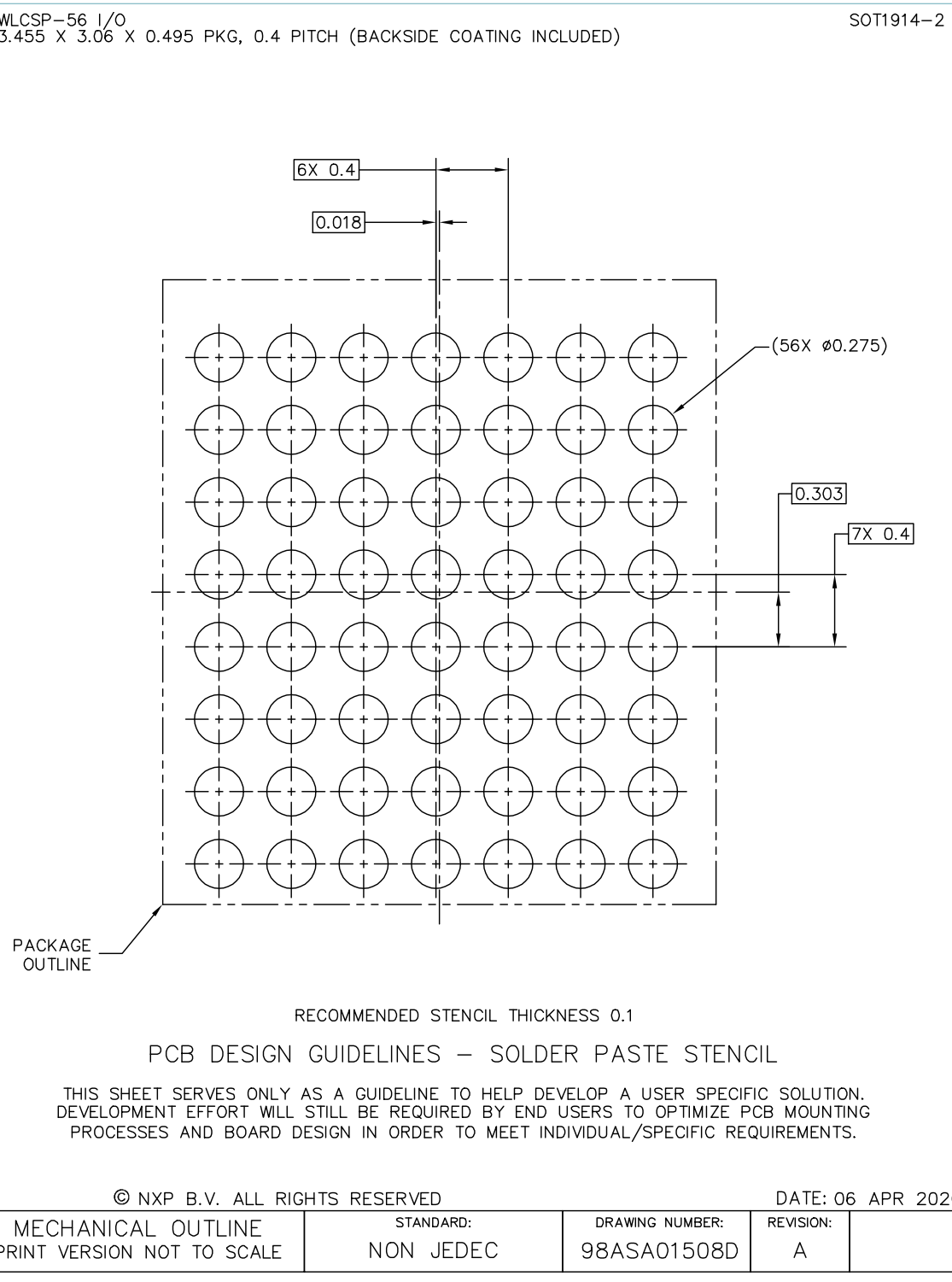

Figure 4. Reflow soldering footprint part3 for WLCSP56 (SOT1914-2)

WLCSP56, wafer level chip-scale package; 56 bumps, 0.4 mm pitch, 3.455 mm x 3.06 mm x 0.495 mm body (backside coating included)

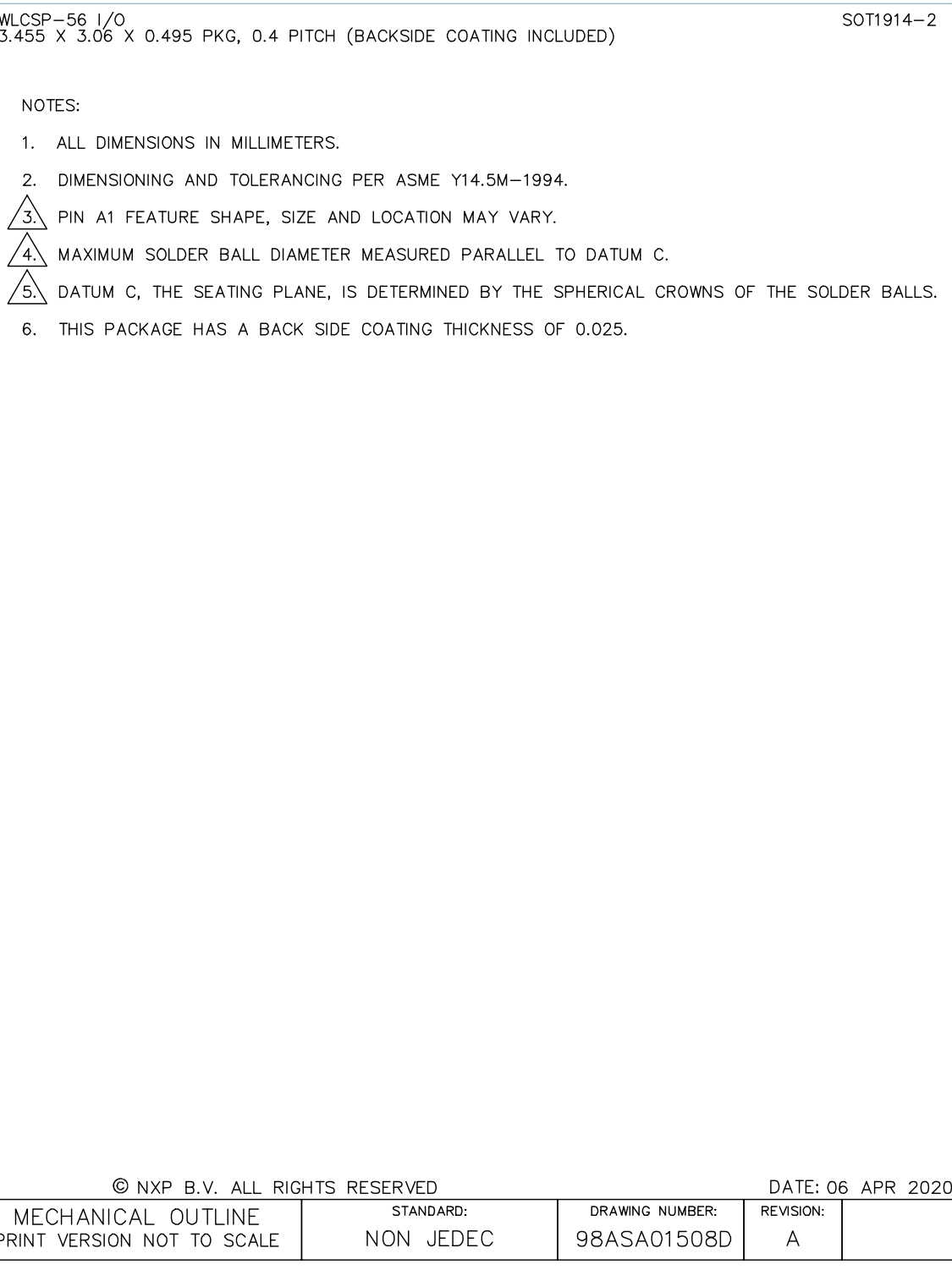

Figure 5. Package outline note WLCSP56 (SOT1914-2)

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WLCSP56, wafer level chip-scale package; 56 bumps, 0.4 mm pitch, 3.455 mm x 3.06 mm x 0.495 mm body (backside coating included)

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Date of release: 6 May 2020